PCN Number:									
	2016030900)2			PCN Date:		te:	3/14/2016	
Title: Datasheet for LMP91200									
Customer Contact:	PCN Manager			Dept:		ot:	Quality Services		
Change Type:									
Assembly Site			Design			Wafer	Bump	Site	
	Assembly Process		Data Sheet]		Bump Material		
Assembly Materials			Part number change				Bump Process		
Mechanical Specification		Щ	Test Site		$\bot\!$		Fab Site		
Packing/Shipping/Labeling			Test Process		4		Fab Materials		
							Fab F	Fab Process	
Notification Details									
Description of Change: Texas Instruments Incorporated is announcing an information only notification.									
The following change	. ,		ted as summarized belovurther details.	v.					
TEXAS INSTRUMENTS SNAS571E – JANUARY 2012 – REVISED FEBRUARY					LMP91200 BRUARY 2016				
Deleted SPI Function								Page1	
The datasheet number	will be chang	ing	•						
Device Family	Device Family			Change From:			Change To:		
LMP91200			SNAS571D				SNAS571E		
	reviewed at t	۔ ۔ا،							
These changes may be http://www.ti.com/pro			datasneet links provided						
http://www.ti.com/pro	oduct/LMP9120	<u>)0</u>							
http://www.ti.com/pro Reason for Change: To more accurately re	oduct/LMP9120	o <u>o</u> ara	cteristics.						
http://www.ti.com/pro Reason for Change: To more accurately re	oduct/LMP9120	o <u>o</u> ara			ty	(posit	ive /	negative):	
Reason for Change: To more accurately reason for Change: No anticipated impact to the actual device.	flect device characteristics on Fit, Form, This is a spec	ara Fu	cteristics. nction, Quality or Relia ation change announcem	abili nent	_				
Reason for Change: To more accurately reason for Change: No anticipated impact to the actual device.	flect device characteristics on Fit, Form, This is a spec	ara Fu	cteristics. nction, Quality or Relia	abili nent	_				
Reason for Change: To more accurately reason for Change: No anticipated impact to the actual device.	flect device characteristics on Fit, Form, This is a spec	ara Fu	cteristics. nction, Quality or Relia ation change announcem	abili nent	_				
Reason for Change: To more accurately rei Anticipated impact of No anticipated impact to the actual device. Changes to product	flect device characteristics on Fit, Form, This is a spec	ara Fu	cteristics. nction, Quality or Relia ation change announcem	abili nent	_				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com